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(54) **HEATER APPARATUS FOR A COMPUTING DEVICE**

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(57) **ABSTRACT**

A computing device includes a printed circuit board, a base, and a heater apparatus. The printed circuit board is secured to the base. The heater apparatus includes a heater component and a plurality of heater wires, and the heater component is disposed between the printed circuit board and the base.

Information
Handling
System
100

